



FAISAL AHAMED-STAFF/BLACK BELT-ENGINEER

+601137068683 | faisalking3rd@gmail.com | Kuala Lumpur, Malaysia | linkedin.com/in/faisal-ahamed-876aa417 |
www.jobstreet.com.my/profile/faisal-ahamed-fF8JzKJhQZ | profile.indeed.com/p/faisalm-gikcizu

PROFESSIONAL SUMMARY

In carrier span 24 years received 17 Technical Excellence Awards from plant wide, Diamond Chip Award highest level recognition from CEO, and Six Sigma Green Belt/Black Belt certification from CEO. Qualified more 50 NPI/NTI products from design stage. Pioneered first integrated DC load board solution with life time revenue >USD 200 million.

EDUCATION

Universiti Malaya (UM)
Bachelor's, Electrical Engineering

CERTIFICATIONS

- C++ Certification : January 2002 • Green Belt Certification: December 2005
- Black Belt Certification: January 2010 • NI Certified Test Code and Test Plan Developer: December 2023

PROFESSIONAL EXPERIENCE

NXP Malaysia Sdn Bhd

Staff Black Belt Product Engineer

Petaling Jaya, SGR, Malaysia

January 2016 - March 2024

- Architected dc load board design for NTI package OM4008, LGA(4x4.5mm, 6x7.5mm, 7x10mm), PQFN(8x8mm) which enabled 100% conversion to new 20 Juno testers without business disconnect in 2019 and honored with multiple TEA awards
- Led a diverse team of 5 specialists across Leaded, BGA, RF, Sensor, and Quality; formed a plantwide DMAIC team that excelled in reducing customer quality complaints by 50% in 2018, garnering several accolades.
- Coordinated a multi-functional team from engineering, design, manufacturing, and quality assurance for Macro GAN NPI in SOE package, achieving \$200M in lifetime revenue in 2019 with highest ASP in new Gan 4.5 technology
- Spearheaded NTI/NPI product in 7x10mm DMS module GAN in 2020 which translated to USD 100 million in sales and enabled 10 testers duplicated for increased run rates
- Engineered the first PLD package from Cassini platform to NI platform in 2021 to increase capacity by reducing test time by 25%
- Launched state of the art NTI (New Technology Introduction) top cooling heatsink package Triseca(14x10mm) and secured socket win of USD 68 million in 2019
- Championed test program development and DC hardware readiness for state of the art NTI 20x16mm mid-power module which translated to USD 120 million revenue in 2024.
- Introduced more than 50 NPIs with high gross margins and significantly contributed to company revenue growth from 2000 to 2024
- Facilitated customer quality incident on Silicon Germanium digital product line by engaging business group in which the product launched with quality fix to memory read/write error with sales of 2 million parts with USD 40 million revenue from January 2022 to December 2023.

Freescall Semiconductor Malaysia Sdn Bhd

Staff Product Engineer

Petaling Jaya, SGR, Malaysia

January 2004 - December 2015

- Resolved customer oscillation complaint on MW4IC2230 and sustained business continuity worth of USD 40 million in 2005 using ADS software and clinched Bronze Medal
- Integrated load board arrangements for MW6IC2240/MW6IC2015 business opportunity of USD 23 Million in 2005 achieved silver medal at plantwide forum
- Implemented DC Check Open/Short at RF tester using sift HTBASIC codes in 2006 to prevent burnt circuits reduced downtime from 2 shifts to nil and secured Bronze Medal
- Innovated RF test time reduction method in 2006 and increased throughput by 2x per shift and en rooted Bronze Medal
- Studied M52A die mask Series Capacitance Nitride Thickness to RF Performance joint collaboration characterization with wafer fab in 2008 and elevated product yield to 99% and reached Bronze Medal

- Eliminated Ruptured DC leaking prevention Cap Escape to Customer-MD7IC2050N in 2010 initiated Bronze Medal and successfully found a unique method of grounding the RF pin and disabled escapee
- Characterized mask L15 Yield Improvement (Black belt Project) through innovative Direct Current load board routing using statistical approach in 2011 and drafted Bronze Medal and demonstrated significant cost saving of USD 250K per annum
- Developed MD7IC2050 pristine DC Board with 4 Point Kelvin System in 2011 and listed Silver Medal by improving VDs on accuracy by 50% through innovative force and sense design principle
- Overhauled MR6VP3091 symmetrical lead shorting test Escapee to Customer by successfully recalibrated DC load board structure and accompanied by software changes to detect shorted leads through innovative test program in 2011 securing distinguished Bronze Medal
- Executed Gross Margin improvement for RFIC Platform in 2013, capturing Bronze Medal for elevating test yield from 94% to 99% by eradicating ESD issues, achieving annual cost savings of \$400K.

Motorola Malaysia Sdn Bhd

Senior Product Engineer

Petaling Jaya, SGR, Malaysia

January 2000 - December 2003

- Enhanced test capability for HPA (High Power Amplifier) by developing in-line tuning using 3 equipment namely network analyzer, spectrum, and signal generator with lifetime revenue of USD 200 million which conferred Bronze Medal in 2003.
- Revamped the PA MHPA18010, boosting capability enhancement quality index from 0.5 to 1.67, facilitating device qualification with \$250 million revenue, and securing a green belt DMADV project certification for exceptional statistical methodology in 2004.

PROJECTS & OUTSIDE EXPERIENCE

Technical Excellence Awards Recognition

January 2003 - March 2024

Petaling Jaya, SGR, Malaysia

- Trisea NTI package 14x10mm test hardware solutions and development with USD68 million life time revenue in 2023- Bronze Medal
- Both Delta 1688 handler and Turret Handler integration to Juno DC tester thru dc interface board in 2017- Bronze Medal
- AFT20S015N Poka Yoke Solution for Wrong Orientation Detection in 2015- Bronze Medal
- New Juno Tester DC Interface Design For Entire TO platform in 2015- Bronze Medal.
- Gross Margin improvement for RFIC Platform in 2013- Bronze Medal
- Total Factory Wire Bond Quality Improvement in 2013- Bronze Medal
- Error Proof MR6VP3091 adjacent lead shorting test excursion to customer in 2011- Bronze Medal
- MD7IC2050 New DC load Board Development with 4 Point Kelvin System 2011- Silver Medal
- L15 Yield Improvement Black belt Project using DMAIC approach in 2010- Bronze Medal
- Elimination of Ruptured DC blocking Cap Escape to Customer-MD7IC2050N in 2010- Bronze Medal
- M52A die mask Series Capacitance Nitride Thickness to RF Performance Characterization in 2008 - Bronze Medal
- RF test time improvement using innovative method in 2006 - Bronze Medal
- Fool Proof Burnt Circuit Elimination Thru RF Software Optimization in 2006- Bronze Medal
- Integrated Load Board Design MW6IC2240/MW6IC2015 in 2005- Silver Medal
- MW4IC2230 Customer JRC Oscillation Complaint in 2005 - Bronze Medal
- MHPA18010 PA Recharacterization in 2004 - Silver Medal
- HPA Next Generation Module in 2003 - Bronze Medal

Cheif Executive Officer/General Manager Awards

January 2015 - December 2016

Petaling, SGR, Malaysia

- Awarded CEO Diamond Chip Award (2015/2016) for production ramp-up in meeting volume.
- Awarded General Manager Bravo Award (2016) for excellence in meeting factory yield goals and actively involved in several key projects benefiting the business group.
- Awarded Peer to Peer award by Chandler USA team for excellent collaboration in 2019.

SKILLS

Skills: MATLAB, Java, Altium, Agile, CAD, C/C++, AutoCAD, Autodesk CFD, Citrix, Excel/Numbers/Sheets, Product Development, Minitab, JMP, Cassini Test Plan/Exec Development, Juno DC test program development, National Instruments Test Code Development, DMAIC, DMADV, 8D, Lean Sigma Coaching, . CAD Software Proficiency (2D and 3D), Experience in Semiconductor Industry, Engineering Education (Bachelor's/Master's Degree), Systematic Problem-Solving Methodology, Project Coordination and Teamwork

Languages: Tamil, Malay